ATT 34 AMOT

CLAIMS

1. A wafer prober which comprises a ceramic substrate and a conductor layer formed on the surface thereof.

5

- 2. The wafer prober according to Claim 1 wherein said conductor layer is a chuck top conductor layer.
- 3. The wafer prober according to Claim 1 or 2 wherein said ceramic substrate is equipped with a temperature control means.
- 4. The wafer prober according to any of Claims 1 to 3 wherein said ceramic substrate is composed of at least one member selected from the group essentially consisting of nitride ceramics, carbide ceramics and oxide ceramics.
 - 5. The wafer prober according to any of Claims 1 to 4 wherein said temperature control means is a Peltier device.

20

- 6. The wafer prober according to any of Claims 1 to 5 wherein said temperature control means is a heating element.
- 7. The wafer prober according to any of Claims 1 to 6 wherein said ceramic substrate has at least one conductor layer therein.
- 8. The wafer prober according to any of Claims 1 to 7 wherein said ceramic substrate is formed with a channel on its surface.
 - 9. The wafer prober according to any of Claims 1 to 8 wherein channels are formed on the surface of said ceramic substrate, the channels being provided with air suction holes.

35

10. The wafer prober according to Claim 1 wherein said conductor layer is a porous layer.